

PMP10503 REV 1 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
IPC B?	1		PMP7896 RevB	Any	PMP7896 RevB	N/A
C1	1	470pF	GRM2165C2A471JA01D	MuRata	CAP, CERM, 470pF, 100V, +/-5%, C0G/NP0, 0805	0805
C2, C3, C4	3	100uF	EEV-FK2A101M	Panasonic	CAP, AL, 100uF, 100V, +/-20%, 0.17 ohm, SMD	SMT Radial J16
C5, C6, C8	3	1uF	C3216X7R2A105M	TDK	CAP, CERM, 1uF, 100V, +/-20%, C Series, 1206	1206
C7	1	100uF	EMVH101GDA101MLH0S	United Chemi-Con	CAP ALUM 100UF 100V 20% SMD	H0S
C9	1	0.1uF	GRM188R72A104KA35D	MuRata	CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0603	0603
C10, C12, C13	3	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603
C11	1	4.7uF	C1608X6S1A475K	TDK Corporation	CAP CER 4.7UF 10V 10% X6S 0603	0603 (1608 Metric)
C14	1	0.047uF	GRM188R71E473KA01D	MuRata	CAP, CERM, 0.047uF, 25V, +/-10%, X7R, 0603	0603
C15	1	0.47uF	GRM21BR72A474KA73L	MuRata	CAP, CERM, 0.47uF, 100V, +/-10%, X7R, 0805	0805
C16	1	0.22uF	GRM188R71E224KA88D	MuRata	CAP, CERM, 0.22uF, 25V, +/-10%, X7R, 0603	0603
C17	1	330pF	C1608C0G1H331J	TDK	CAP, CERM, 330pF, 50V, +/-5%, C0G/NP0, 0603	0603
C18	1	0.022uF	C1608X7R1H223K	TDK	CAP, CERM, 0.022uF, 50V, +/-10%, X7R, 0603	0603
D2	1	0.57V	MBR1H100SFT3G	On Semiconductor	DIODE SCHOTTKY 1A 100V SOD-123FL	SOD-123FL
H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
L1	1	15uH	74435571500	Würth Elektronik eiSos	Inductor, Shielded Drum Core, Ferrite, 15uH, 14A, 0.009 ohm, SMD	18.3x8.9x18.2mm
Q1, Q2, Q3	3	80V	BSC123N08NS3 G	Infineon Technologies	MOSFET, N-CH, 80V, 55A, PG-TDSON-8	PG-TDSON-8
R1	1	7.5	ERJ-12ZYJ7R5U	Panasonic	RESISTOR 7.5 OHM 3/4W 5% 2010	2010
R2	1	0.006	ERJ-M1WSF6M0U	Panasonic	RES, 0.006 ohm, 1%, 1W, 2512	2512
R3, R4	2	100	CRCW0603100RFKEA	Vishay-Dale	RES, 100 ohm, 1%, 0.1W, 0603	0603
R5, R6, R8, R12, R21	5	0	ERJ-3GEY0R00V	Panasonic	RES, 0 ohm, 5%, 0.1W, 0603	0603
R10	1	34.8k	CRCW060334K8FKEA	Vishay-Dale	RES, 34.8k ohm, 1%, 0.1W, 0603	0603
R11	1	3.3	CRCW06033R30JNEA	Vishay-Dale	RES, 3.3 ohm, 5%, 0.1W, 0603	0603
R13	1	7.87k	CRCW06037K87FKEA	Vishay-Dale	RES, 7.87k ohm, 1%, 0.1W, 0603	0603
R14	1	49.9k	CRCW060349K9FKEA	Vishay-Dale	RES, 49.9k ohm, 1%, 0.1W, 0603	0603
R16	1	71.5k	CRCW060371K5FKEA	Vishay-Dale	RES, 71.5k ohm, 1%, 0.1W, 0603	0603
R17	1	59.0k	CRCW060359K0FKEA	Vishay-Dale	RES, 59.0k ohm, 1%, 0.1W, 0603	0603
R18	1	2.15k	CRCW06032K15FKEA	Vishay-Dale	RES, 2.15k ohm, 1%, 0.1W, 0603	0603
R19	1	84.5k	CRCW060384K5FKEA	Vishay-Dale	RES, 84.5k ohm, 1%, 0.1W, 0603	0603
R20	1	3.48	CRCW06033R48FKEA	Vishay-Dale	RES, 3.48 ohm, 1%, 0.1W, 0603	0603
TP1, TP2, TP3, TP4	4		575-8	Keystone	Standard Banana Jack, Uninsulated, 8.9mm	Keystone575-8
TP5, TP7	2	Red	5010	Keystone	Test Point, TH, Multipurpose, Red	Keystone5010
TP6, TP8, TP10	3	Black	5011	Keystone	Test Point, TH, Multipurpose, Black	Keystone5011
TP9, TP11	2	White	5002	Keystone	Test Point, TH, Miniature, White	Keystone5002
TP12	1	White	5012	Keystone	Test Point, TH, Multipurpose, White	Keystone5012
U1	1		LM5122QMH/NOPB	Texas Instruments	Wide Input Synchronous Boost Controller with Multiple Phase Capability, PWP0020A	PWP0020A
D1	0	0.77V	DFLS1100-7	Diodes Inc.	Diode, Schottky, 100V, 1A, PowerDI123	PowerDI123
FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
R7	0	158k	CRCW0603158KFKEA	Vishay-Dale	RES, 158k ohm, 1%, 0.1W, 0603	0603
R9	0	DNP	CRCW06033R30JNEA	Vishay-Dale	RES, 3.3 ohm, 5%, 0.1W, 0603	0603
R15	0	DNP	ERJ-3GEY0R00V	Panasonic	RES, 0 ohm, 5%, 0.1W, 0603	0603

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